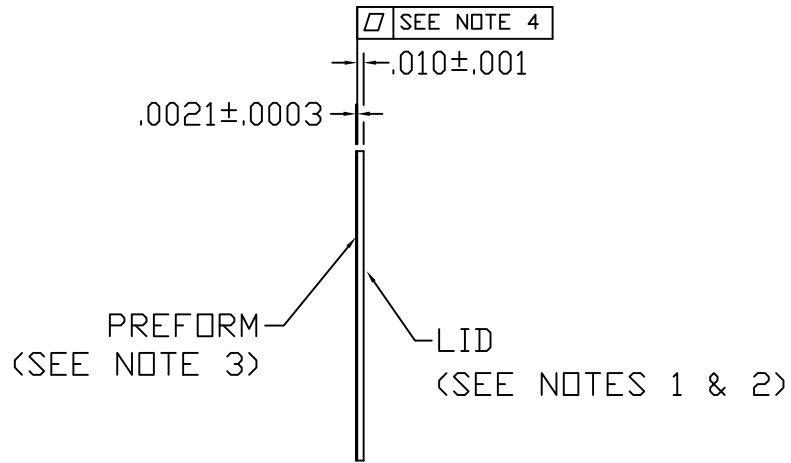
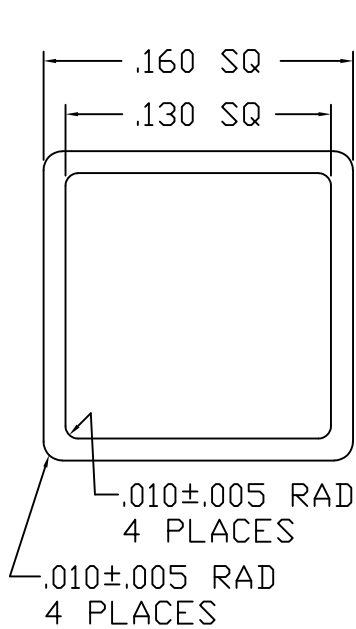


# SSM P/N CL-16005



**NOTES**

1. MAT'L : KOVAR OR ALLOY 42
2. PLATING : 1st LAYER 50/350 MICROINCHES NI  
2nd LAYER Au  
3rd LAYER 50/350 MICROINCHES NI  
4th LAYER 25 MICROINCHES MINIMUM Au

NOTES : TOTAL NICKEL LAYERS SHALL NOT EXCEED 450 MICROINCHES AND THE SUM OF BOTH GOLD LAYERS SHALL BE 50 MICROINCHES MINIMUM.

3. PREFORM - 80% ±1% Au  
20% Sn
4. FLATNESS : ONE MIL (.001) MAXIMUM PER 1/2' T.I.R
5. TOLERANCES TO BE (XXX) 3 PLACES ±.002 UNLESS OTHERWISE NOTED

DESCRIPTION HI REL COMBO LID	Manufactured by: Materion Advanced Materials 2978 Main Street Buffalo, NY 14214
PART NO CL-16005	
Spectrum Semiconductor Materials, Inc. 155 Nicholson Lane San Jose, CA 95134 PH: (408) 435-5555 Fx: (408)435-8226	MFG DRAWING NO: W174H

